



### 30V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8 (SWP) (Type UX)

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>C</sub> = +25°C
	5.0mΩ @ V <sub>GS</sub> = 10V	60A
30V	7.4mΩ @ V <sub>GS</sub> = 4.5V	50A

## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

### **Features and Benefits**

- Low R<sub>DS(ON)</sub> ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

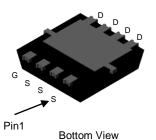
#### **Mechanical Data**

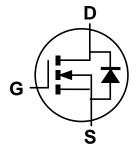
- Case: PowerDI<sup>®</sup>3333-8 (SWP) (Type UX)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208@3
- Weight: 0.072 grams (Approximate)

PowerDI3333-8 (SWP) (Type UX)









**Equivalent Circuit** 

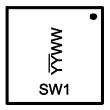
### **Ordering Information** (Note 4)

Part Number	Case	Packaging	
DMN3009LFVW-7	PowerDI3333-8 (SWP) (Type UX)	2,000/Tape & Reel	
DMN3009LFVW-13	PowerDI3333-8 (SWP) (Type UX)	3,000/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



SW1 = Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digit of Year (ex: 17 = 2017)

WW = Week Code (01 to 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	$V_{DSS}$	30	V	
Gate-Source Voltage	$V_{GSS}$	±20	V	
Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V	$T_C = +25$ °C $T_C = +70$ °C	Ι <sub>D</sub>	60 48	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	90	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	Is	60	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	I <sub>SM</sub>	90	А	
Avalanche Current, L = 0.1mH (Note 8)	I <sub>AS</sub>	33	Α	
Avalanche Energy, L = 0.1mH (Note 8)	E <sub>AS</sub>	58	mJ	

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		$P_{D}$	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	126	°C/W
Total Power Dissipation (Note 6)		$P_{D}$	2.0	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ heta JA}$	62	°C/W
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	4.6	C/VV
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

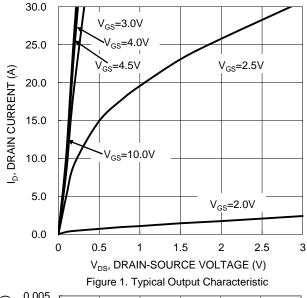
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	1	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	2.5	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance		_	3.5	5.0	mΩ	$V_{GS} = 10V, I_D = 30A$	
Static Dialii-Source Off-Resistance	R <sub>DS(ON)</sub>	_	4.9	7.4	11152	$V_{GS} = 4.5V, I_D = 15A$	
Diode Forward Voltage	$V_{SD}$	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>		2,000	_	pF	15// 1/	
Output Capacitance	Coss	_	315	_	pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	Crss	_	247	_	pF		
Gate Resistance	$R_g$	_	2.2	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	20	1	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	42	_	nC	Vns = 15V. In = 15A	
Gate-Source Charge	$Q_{gs}$	_	4.7	_	nC	V <sub>DS</sub> = 15V, I <sub>D</sub> = 15A	
Gate-Drain Charge	$Q_{gd}$	_	7.4	_	nC	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.9	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$ $R_{G} = 3.3\Omega, I_{D} = 15A$	
Turn-On Rise Time	t <sub>R</sub>	_	4.1	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	31	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	15	_	ns		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	15	_	ns	I <sub>F</sub> = 15A, di/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	6.0	_	nC		

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_{J}$  = +25°C.
- Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.





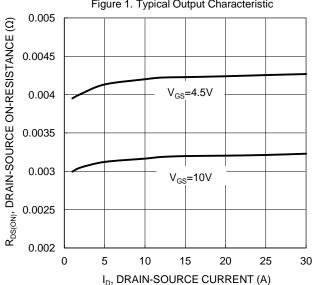


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

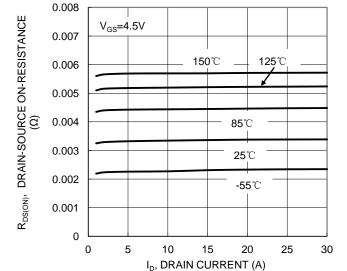
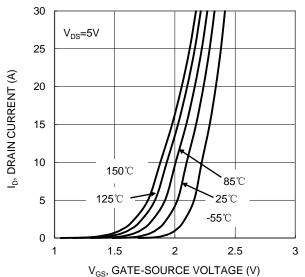
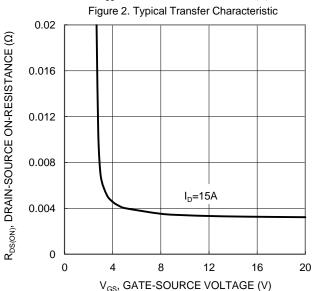


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





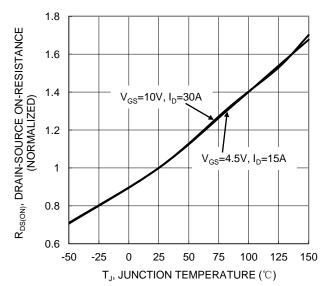


Figure 4. Typical Transfer Characteristic

Figure 6. On-Resistance Variation with Temperature



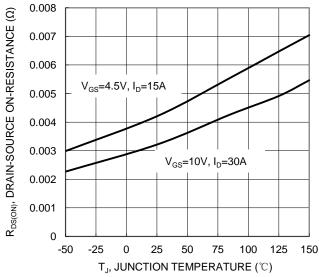


Figure 7. On-Resistance Variation with Temperature

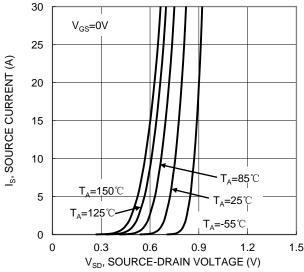
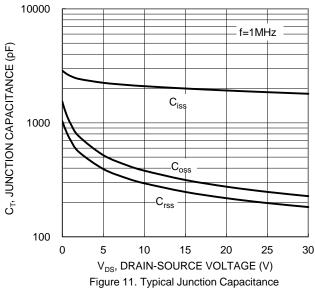


Figure 9. Diode Forward Voltage vs. Current



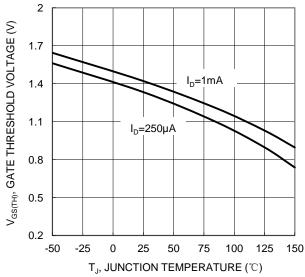


Figure 8. Gate Threshold Variation vs. Junction Temperature

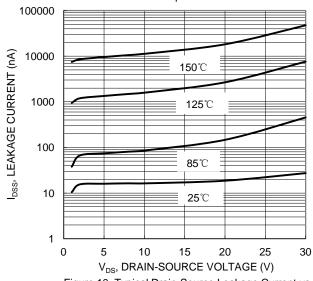


Figure 10. Typical Drain-Source Leakage Current vs. Voltage

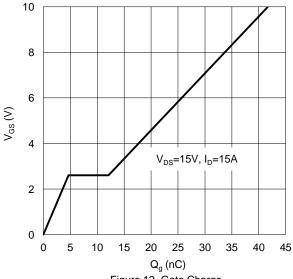
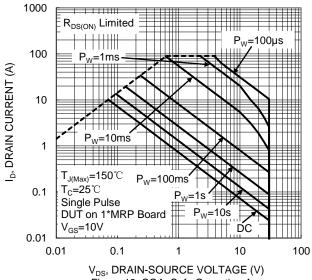


Figure 12. Gate Charge





 $V_{\rm DS}$ , DRAIN-SOURCE VOLTAGE (V) Figure 13. SOA, Safe Operation Area

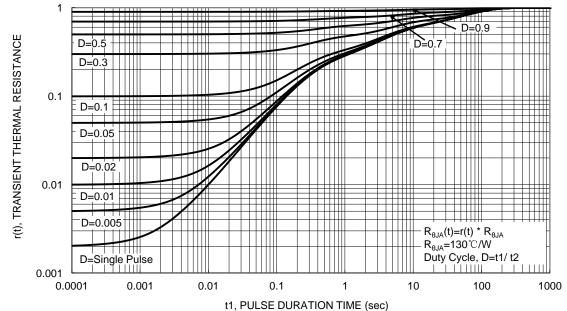


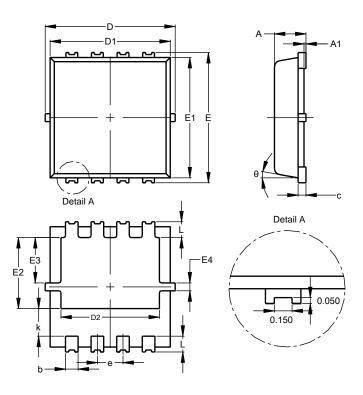
Figure 14. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)

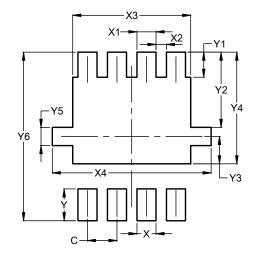


PowerDI3333-8 (SWP)						
(Type UX)						
Dim	Min	lin				
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)



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Dimensions	Value (in mm)		
С	0.650		
Х	0.420		
X1	0.420		
X2	0.230		
Х3	2.600		
X4	3.500		
Υ	0.700		
Y1	0.550		
Y2	1.650		
Y3	0.600		
Y4	2.450		
Y5	0.400		
Y6	3.700		



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